

Title (en)

METHOD FOR MANUFACTURING AN ELECTRONIC PACKAGE

Title (de)

HERSTELLUNGSVERFAHREN FÜR EIN ELEKTRONISCHES GEHÄUSE

Title (fr)

PROCÉDÉ POUR FABRIQUER UN BOÎTIER ÉLECTRONIQUE

Publication

EP 2537400 A1 20121226 (FR)

Application

EP 11703690 A 20110215

Priority

- EP 10305158 A 20100216
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Abstract (en)

[origin: EP2357875A1] The method involves arranging (S1) a chip (1) on a trailed adhesive support (2), and molding (S2) resin (3) for coating the chip on the support. An island zone (10) is turned over (S3), so that the chip has exposed active face, where the island zone is formed by the assembly of the chip and resin. A conductive material is applied on the turned island zone for materializing a contact pad connecting a contact point (1a) of the chip to an exterior medium. Independent claims are also included for the following: (1) a system for manufacturing an electronic case, comprising an arranging unit (2) an electronic case comprising a chip.

IPC 8 full level

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CPC (source: EP)

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Citation (search report)

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